

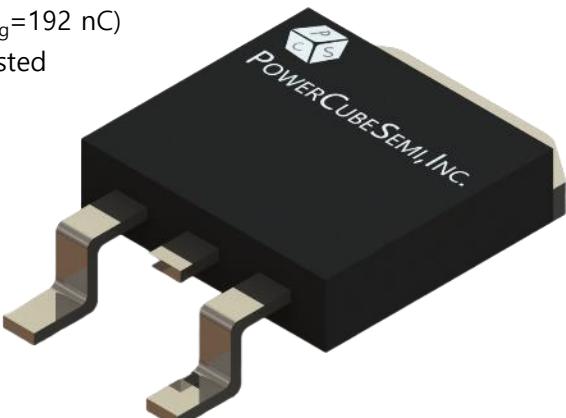
PM007N100DG

100V 140A 4.4mΩ Si Single N-ch Enhancement Mode Power MOSFET with Normal Diode

Features

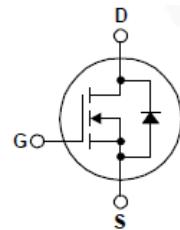
Si Single N-ch Enhancement Mode Power MOSFET

- Rated to 100V at 140Amps @ $T_J = 25^\circ\text{C}$
- Max $R_{DS(on)} = 7.5 \text{ m}\Omega$
- Typ $R_{DS(on)} = 5.6 \text{ m}\Omega$
- Gate Charge(Typ. $Q_g = 192 \text{ nC}$)
- 100% Avalanche Tested



Application

- Power Switch
- DC/DC Converter



PKG type : TO-263 (D2PAK)

Description

The PM007N100DG uses advanced trench Technology to provide excellent $R_{DS(ON)}$, low gate charge. it can be used in a wide variety of applications.

Absolute Maximum Ratings

Symbol	Parameter	Test Condition	Value	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	100	V
I_D	Drain Current	$T_c=25^\circ\text{C}$	140	A
I_{DM}	Pulsed Drain Current	Pulse width limited by junction temperature	560	A
V_{GS}	Gate-Source Voltage		± 20	V
E_{AS}	Single Pulsed Avalanche Energy	$V_{DD}=50\text{V}, V_{GS}=10\text{V}, L=0.5\text{mH}, R_G=25\Omega$	361	mJ
P_d	Power Dissipation	$T_c=25^\circ\text{C}$	236	W
T_j	Operating Junction Temperature		150	°C
T_{stg}	Storage Temperature		-55 to 150	°C



Package Marking and Ordering Information

Device Marking	Device	Package	Packing Method	Tape width	Quantity
PM007N100DG	PM007N100	TO-263	REEL	-	800

Electrical Characteristics of Si MOSFET

Symbol	Parameter	Test Condition	Numerical			Unit
			Min	Typ.	Max.	
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A, T_J = 25^\circ C$	100	-	-	V
I_{DSS}	Zero gate voltage drain current	$V_{DS} = 100V, V_{GS} = 0V$	-	-	1	μA
I_{GSS}	Gate-source leakage current	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	± 100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.0	1.7	2.5	V
$R_{DS(ON)}$	Static drain-source on state resistance	$V_{GS} = 10V, I_D = 30A$	-	5.6	7.5	$m\Omega$
g_{FS}	Forward transconductance	$V_{DS} = 5V, I_D = 30A$	-	59	-	S
$t_{d(on)}$	Turn-on Delay time	$V_{DS} = 50 V, I_D = 30A, R_G = 4.7\Omega$	-	32	-	ns
T_r	Turn-on Rise time		-	118	-	
$t_{d(off)}$	Turn-off Delay time		-	80	-	
T_f	Turn-off Fall time		-	27	-	



Electrical Characteristics of Si MOSFET

Symbol	Parameter	Test Condition	Numerical		Unit
			Typ.	Max.	
$R_{\theta JC}$	Thermal resistance, Junction to case		0.53	-	°C/W
C_{iss}	Input capacitance	$V_{DS} = 50V, V_{GS} = 0V, f = 1.0MHz$	13950	-	pF
C_{oss}	Output capacitance		432	-	
C_{rss}	Reverse transfer capacitance		362	-	
$Q_{g(tot)}$	Total gate charge at 10V	$V_{DS} = 50V, I_D = 30A, V_{GS(on)} = 10V$	192	-	nC
Q_{gs}	Gate to source gate charge		49	-	
Q_{gd}	Gate to drain "Miller" charge		23	-	

Electrical Characteristics of Si Diode

Symbol	Parameter	Test Condition	Numerical		Unit
			Typ.	Max.	
I_S	Maximum continuous drain to source diode forward current		-	140	A
V_{SD}	Drain to source diode forward voltage	$I_S = 30A, V_{GS} = 0V$	-	1.2	V
T_{rr}	Reverse recovery time	$I_F = 30A, V_{GS} = 0V, dI_F/dt = 100A/\mu s$	96	-	ns
Q_{rr}	Reverse recovery charge		212	-	nC

Typical Characteristics

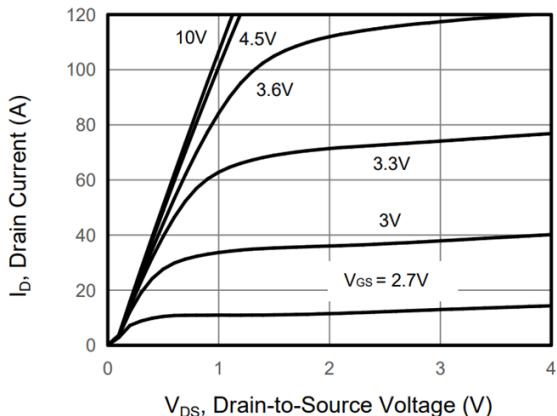


Figure 1. Output Characteristics

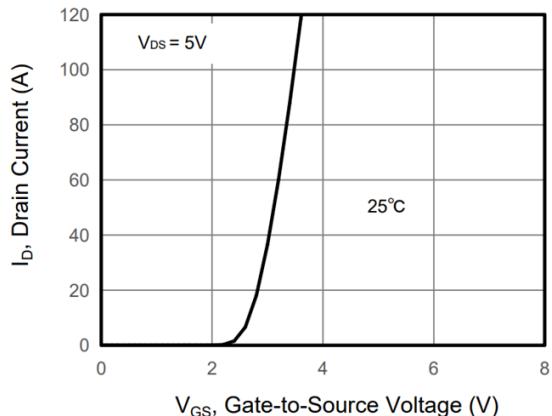


Figure 2. Transfer Characteristics

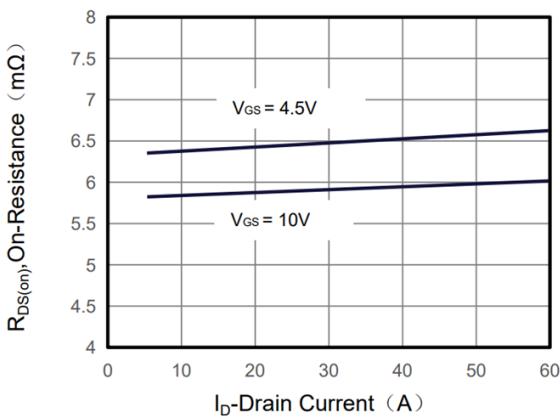


Figure 3. Drain to Source On-Resistance

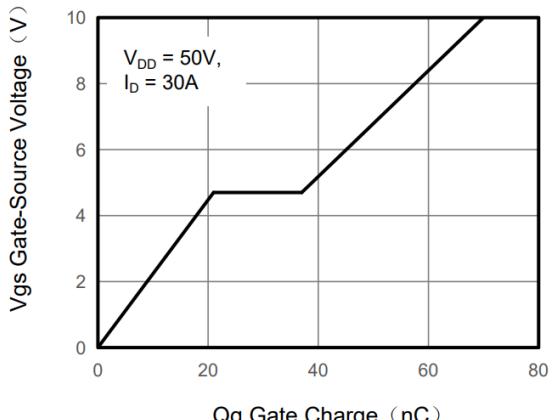


Figure 4. Gate Charge

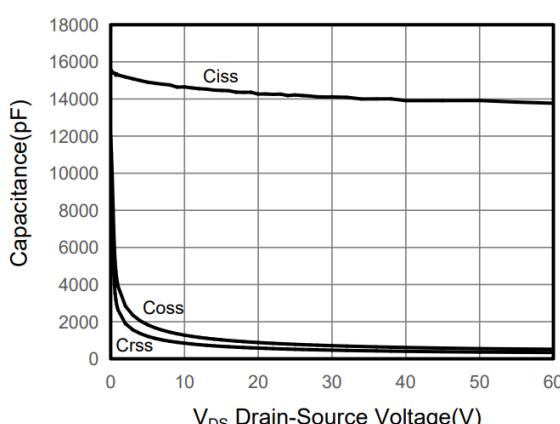


Figure 5. Capacitance Characteristics

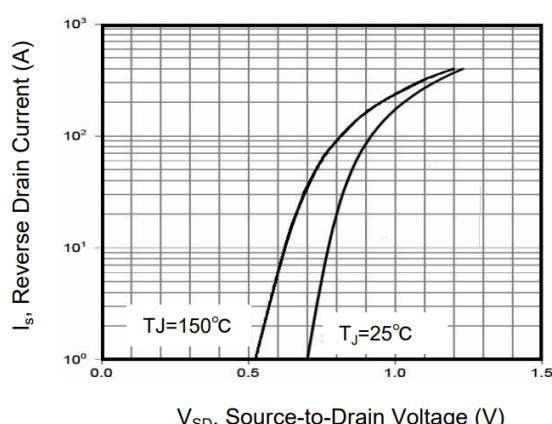


Figure 6. Source to Drain Diode Forward

Typical Characteristics

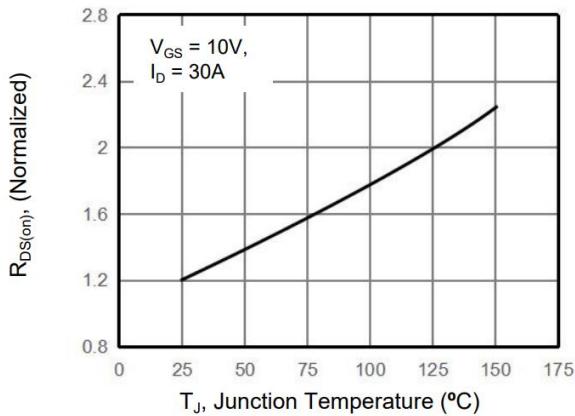


Figure 7. Drain to Source On-Resistance

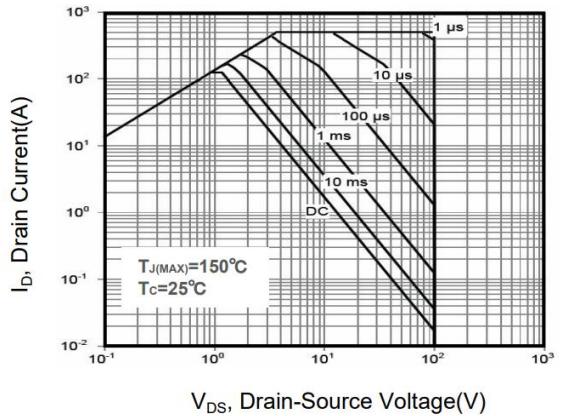


Figure 8. Safe Operation Area

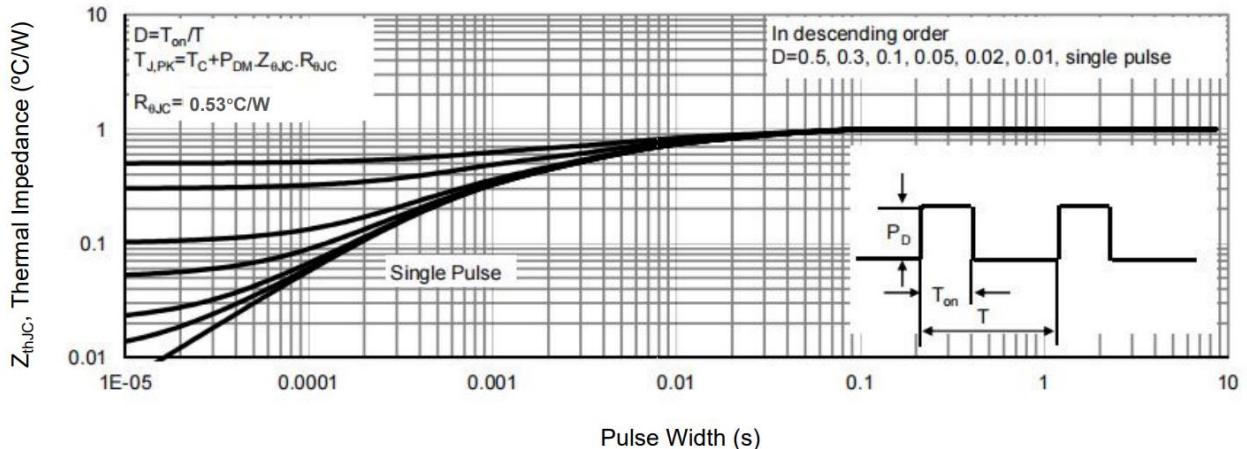
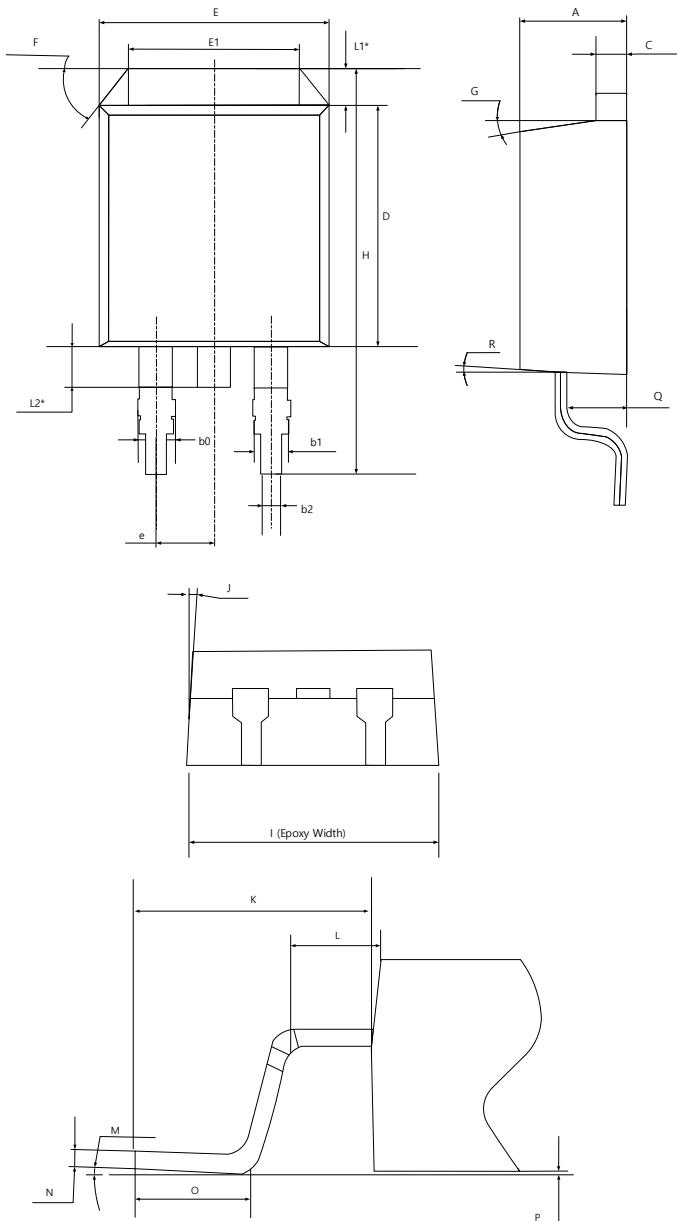


Figure 9. Normalized Maximum Transient Thermal Impedance



Package Outline



Unit : mm

SYMBOL	DIMENSIONS		
	MIN	NOM	MAX
A	4.40	4.60	4.80
b0	1.17	1.37	1.57
b1	1.17	1.27	1.37
b2	0.70	0.80	0.90
C	1.17	1.27	1.37
D	8.50	8.70	8.90
E	9.80	10.00	10.20
E1	6.50	-	-
e	2.44	2.54	2.64
F	-	30° (Ref)	-
G	-	7.0°	-
H	15.00	15.30	15.60
I	9.80	10.00	10.20
J	-	3.0°	-
K	5.00	5.30	5.60
L	1.80	2.00	2.20
L1	1.07	1.27	1.47
L2	1.20	1.50	1.80
M	0.0°	-	8.0°
N	0.30	0.45	0.60
O	2.34	2.54	2.74
P	0	-	0.25
Q	2.37	2.67	2.97
R	-	7.0°	-